

Abstract Submitted
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Glancing Angle Deposition of Cu on Si¹ DUSTIN KERN, LENU ZAMAN, SEAN GEPHART, ANURA GOONEWARDENE, DONGDONG JIA, Department of Geology and Physics, Lock Haven University of Pennsylvania, LHUP NANOTECH GROUP TEAM — Glancing angle deposition technique is a technique that putting the incident flux of source materials at a glancing angle to the substrate during deposition. The so-called shadowing effect can create various kinds of nano or micro structures on the substrate. For glancing angle deposition, the deposition can be thermal vapor deposition, pulsed laser deposition and magnetron deposition. In this work, copper was deposited on silicon substrate by using a magnetron sputtering technique at a glancing angle. The growth mechanism and morphology of the Cu film were analyzed by using a scanning electron microscope.

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